

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6701A/BxxxPR-G
Typical Mass: 57 mg

| Part name | Weight(mg) | Material name | Ratio(ppm) | CAS number |
|--------------|------------|-----------------|------------|------------|
| Silicon chip | 0.617 | Silicon | 10800 | 7440-21-3 |
| | | | | |
| Leadframe | 24.392 | Copper | 427900 | 7440-50-8 |
| | 0.016 | Tin | 300 | 7440-31-5 |
| | 0.218 | Silver | 3800 | 7440-22-4 |
| | | | | |
| Die attach | 0.126 | Silver | 2200 | 7440-22-4 |
| | 0.032 | Epoxy | 600 | — |
| | | | | |
| Bonding wire | 0.030 | Gold | 500 | 7440-57-5 |
| | | | | |
| Resin | 26.926 | Silica | 472400 | 60676-86-0 |
| | 2.197 | Epoxy resin | 38500 | — |
| | 1.586 | Phenol resin | 27800 | — |
| | 0.430 | Metal hydroxide | 7500 | — |
| | | | | |
| Plating | 0.430 | Tin | 7500 | 7440-31-5 |
| | | | | |

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."